

1-5. (withdrawn)

6. (currently amended) A method of manufacturing a self-light-emitting device, comprising the steps of:

filling a nozzle with an application liquid for forming an EL layer; and

continuously applying ~~discharging~~ said application liquid to a pixel column by ultrasonic oscillations.

7. (original) A method of manufacturing a self-light-emitting device according to claim 6, wherein:

said nozzle has a large internal diameter portion and a small internal diameter portion;

said small internal diameter portion has a heater; and

said heater applies heat to the application liquid filling the nozzle.

8-9. (withdrawn)

10. (previously presented) A method of manufacturing a self-light-emitting device according to claim 6, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

11. (currently amended) A method of manufacturing a self-light-emitting device according to claim 6, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, ~~the a~~ a

weight of said application liquid and a pressure, and is applied.

12. (previously presented) A method of manufacturing a self-light-emitting device according to claim 19, wherein said application liquid filling said nozzle is applied by contacting a contact element of said nozzle with said bank.

13-18. (cancel)

19. (previously presented) A method of manufacturing a light-emitting device according to claim 6, wherein said self-light-emitting device comprises a pixel electrode over a substrate and a bank covering at least an edge portion of said pixel electrode over said substrate.

20. (currently amended) A method of manufacturing a light-emitting device comprising:

filling a nozzle with an application liquid for forming an EL layer; and

continuously applying ~~discharging~~ said application liquid to a pixel column by ultrasonic oscillations and heat.

21. (previously presented) A method of manufacturing a light-emitting device according to claim 20, wherein said nozzle has a large internal diameter portion and a small internal diameter portion, said small internal diameter portion has a

heater, and said heater applies heat to the application liquid filling the nozzle.

22. (previously presented) A method of manufacturing a light-emitting device according to claim 20, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

23. (currently amended) A method of manufacturing a light-emitting device according to claim 20, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, ~~the~~ a weight of said application liquid, and a pressure, and is applied.

24. (previously presented) A method of manufacturing a light-emitting device according to claim 20, wherein said light-emitting device comprises a pixel electrode over a substrate and a bank covering at least an edge portion of said pixel electrode over said substrate.

25. (previously presented) A method of manufacturing a light-emitting device according to claim 24, wherein said application liquid filling said nozzle is applied by contacting a contact element of said nozzle with said bank.

26. (currently amended) A method of manufacturing a light-emitting device comprising:

forming a thin film transistor over a substrate;

forming an insulating film over said thin film transistor;
forming a pixel electrode over said insulating film;
forming a bank covering at least an edge portion of said
pixel electrode over said insulating film;

filling a nozzle with an application liquid for forming an
EL layer; and

continuously ~~applying~~ discharging said application liquid
to a pixel column by ultrasonic oscillations.

27. (previously presented) A method of manufacturing a
light-emitting device according to claim 26, wherein said nozzle
has a large internal diameter portion and a small internal
diameter portion, said small internal diameter portion has a
heater, and said heater applies heat to the application liquid
filling the nozzle.

28. (previously presented) A method of manufacturing a
light-emitting device according to claim 26, wherein said
application liquid is pushed out from said nozzle by
pressurization, and is applied.

29. (currently amended) A method of manufacturing a light-
emitting device according to claim 26, wherein said application
liquid is pushed out from said nozzle by a medium selected from
a group consisting of capillary action, ~~the~~ a weight of said
application liquid, and a pressure, and is applied.

30. (previously presented) A method of manufacturing a light-emitting device according to claim 26, wherein said application liquid filling said nozzle is applied by contacting a contact element of said nozzle with said bank.

Further, please add the following new claims 31 to 47.

31. (New) A method of manufacturing a self-light-emitting device, comprising the steps of:

filling a nozzle with an application liquid for forming an EL layer; and

continuously discharging said application liquid to a pixel column by ultrasonic oscillations with scanning the nozzle along a direction parallel to the pixel column.

32. (New) A method of manufacturing a self-light-emitting device according to claim 31, wherein:

said nozzle has a large internal diameter portion and a small internal diameter portion;

said small internal diameter portion has a heater; and

said heater applies heat to the application liquid filling the nozzle.

33. (New) A method of manufacturing a self-light-emitting device according to claim 31, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

34. (New) A method of manufacturing a self-light-emitting device according to claim 31, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, a weight of said application liquid and a pressure, and is applied.

35. (New) A method of manufacturing a self-light-emitting device according to claim 31, wherein said application liquid filling said nozzle is applied by contacting a contact element of said nozzle with said bank.

36. (New) A method of manufacturing a light-emitting device according to claim 31, wherein said self-light-emitting device comprises a pixel electrode over a substrate and a bank covering at least an edge portion of said pixel electrode over said substrate.

37. (New) A method of manufacturing a light-emitting device comprising:

filling a nozzle with an application liquid for forming an EL layer; and

continuously discharging said application liquid to a pixel column by ultrasonic oscillations and heat with scanning the nozzle along a direction parallel to the pixel column.

38. (New) A method of manufacturing a light-emitting device according to claim 37, wherein said nozzle has a large internal

diameter portion and a small internal diameter portion, said small internal diameter portion has a heater, and said heater applies heat to the application liquid filling the nozzle.

39. (New) A method of manufacturing a light-emitting device according to claim 37, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

40. (New) A method of manufacturing a light-emitting device according to claim 37, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, a weight of said application liquid, and a pressure, and is applied.

41. (New) A method of manufacturing a light-emitting device according to claim 37, wherein said light-emitting device comprises a pixel electrode over a substrate and a bank covering at least an edge portion of said pixel electrode over said substrate.

42. (New) A method of manufacturing a light-emitting device according to claim 37, wherein said application liquid filling said nozzle is applied by contacting a contact element of said nozzle with said bank.

43. (New) A method of manufacturing a light-emitting device comprising:

forming a thin film transistor over a substrate;

forming an insulating film over said thin film transistor;
forming a pixel electrode over said insulating film;
forming a bank covering at least an edge portion of said
pixel electrode over said insulating film;

filling a nozzle with an application liquid for forming an
EL layer; and

continuously discharging said application liquid to a pixel
column by ultrasonic oscillations with scanning the nozzle along
a direction parallel to the pixel column.

44. (New) A method of manufacturing a light-emitting device
according to claim 43, wherein said nozzle has a large internal
diameter portion and a small internal diameter portion, said
small internal diameter portion has a heater, and said heater
applies heat to the application liquid filling the nozzle.

45. (New) A method of manufacturing a light-emitting device
according to claim 43, wherein said application liquid is pushed
out from said nozzle by pressurization, and is applied.

46. (New) A method of manufacturing a light-emitting device
according to claim 43, wherein said application liquid is pushed
out from said nozzle by a medium selected from a group
consisting of capillary action, a weight of said application
liquid, and a pressure, and is applied.

47. (New) A method of manufacturing a light-emitting device according to claim 43, wherein said application liquid filling said nozzle is applied by contacting a contact element of said nozzle with said bank.